

IN THE CLAIMS:

The following is a complete list of the claims now pending. This listing replaces all earlier versions and listings of the claims.

1. (Currently Amended) A solid-state image pickup device comprising:
  - a supporting substrate, provided with no wiring;
  - a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted, said solid-state image device pickup element chip being formed on a light incident side of said supporting substrate;
  - a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip; and
  - a wiring substrate formed of a flexible material and connected electrically to said solid-state image pickup element chip,wherein a connection between said solid-state image pickup element chip and said wiring substrate is fixed only at a bump formed on an electrode pad, and  
wherein said supporting substrate ~~that is provided with no wiring~~ has a thermal expansion coefficient substantially equal to that of said protection cap, and said supporting substrate ~~that is provided with no wiring~~ and said protection cap are sealed with a sealing resin, so as to form a structure having a hollow space between said solid-state image pickup element chip and said protection cap.

2. - 6. (Cancelled)

7. (Currently Amended) A solid-state image pickup device comprising:  
a supporting substrate, provided with no wiring;  
a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted, said solid-state image device pickup element chip being formed on a light incident side of said supporting substrate;  
a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip; and  
a wiring substrate formed of a flexible material and connected electrically to said solid-state image pickup element chip,  
wherein a connection between said solid-state image pickup element chip and said wiring substrate is fixed only at a bump formed on an electrode pad, and  
wherein said supporting substrate ~~that is provided with no wiring~~ is made of the same material as that of said protection cap, and said supporting substrate ~~that is provided with no wiring~~ and protection cap are sealed with a sealing resin, so as to form a substrate having a hollow space between said solid-state image pickup element chip and said protection cap.

8. - 12. (Cancelled)

13. (Previously Presented) The device according to claim 1, wherein on said protection cap, an optical low pass filter or an infrared rays cut filter is formed.

14. (Previously Presented) The device according to claim 1, wherein at a periphery of said protection cap, a light shielding layer is formed.

15. - 16. (Cancelled)

17. (Currently Amended) The device according to claim 1, wherein said solid-state image pickup element chip is adhered onto said supporting substrate ~~that is provided with no wiring~~, with a flexible adhesive.

18. (Cancelled)

19. (Currently Amended) The device according to claim 1, wherein said supporting substrate ~~that is provided with no wiring~~, is one of a glass substrate, a ceramic substrate, a metal substrate, a resin substrate, or a substrate formed by stacking two or more of glass, ceramic, metal, and resin substrates.

20. (Previously Presented) The device according to claim 1, wherein said sealing resin is a resin selected from the group consisting of epoxy, acrylic, and phenol-based resins.

21. (Currently Amended) The device according to claim 1, further comprising a light-shielding layer, and wherein said solid-state image pickup element chip is formed on said supporting substrate ~~that is provided with no wiring~~ with said light-

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shielding layer between said supporting substrate ~~that is provided with no wiring~~ and said solid-state image pickup element chip.

22. - 23. (Cancelled)

24. (Currently Amended) The device according to claim 7, wherein said solid-state image pickup element chip is adhered onto said supporting substrate ~~that is provided with no wiring~~, with a flexible adhesive.

25. (Cancelled)

26. (Currently Amended) The device according to claim 7, wherein ~~[[the]] supporting substrate that is provided with no wiring,~~ is one of a glass substrate, a ceramic substrate, a metal substrate, a resin substrate, or a substrate formed by stacking two or more of glass, ceramic, metal, and resin substrates.

27. (Previously Presented) The device according to claim 7, wherein said sealing resin is a resin selected from the group consisting of epoxy, acrylic, and phenol-based resins.

28. (Currently Amended) The device according to claim 7, further comprising a light-shielding layer, and wherein said solid-state image pickup element chip is formed on said supporting substrate ~~that is provided with no wiring~~ with said light-

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shielding layer between said supporting substrate and said solid-state image pickup element chip.

29. (Previously Presented) The device according to claim 7, wherein said light-shielding layer is formed of a light shielding and flexible adhesive.